

## REMARKS

This Amendment is in response to the Office Action dated June 21, 2005. Claims 1-19 are pending in the present application. Claims 1-19 are rejected. Claims 1-2, 7, 9, 13 and 18 have been amended. Claims 3-5, 8, 10-12, 14-15, 17 and 19 have been cancelled. Accordingly, Claims 1-2, 6, 7, 9, 13, 16 and 18 remain pending in the present application.

Applicant requests a three month extension of time from September 22, 2005 to December 21, 2005 to respond to the office action.

### Abstract

A substitute Abstract is provided to provide a concise statement of the technical disclosure.

### Specification

Applicant submits herewith a substitute specification. The substitute specification includes no new matter. Applicant submits both a marked-up version of the specification with markings to show all the changes relative to the immediate prior version and a clean version of the substitute specification.

### Drawings

Applicant has amended the specification to conform to the drawings.

Claim Rejections – 35 USC 112

The Examiner states,

**Claims 1-19 are rejected under 35 USC 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which application regards as the invention.**

Applicant has amended claims 1, 2, 7, 9, 13 and 18 to more particularly point out and distinctly claim the present invention. Applicant has corrected the antecedent basis of the claims and removed language that was not relevant to the claims.

Present Invention

A method for providing an improved integrated circuit device is disclosed. The method comprises the steps of providing active and passive areas in the substrate, providing a plurality of slots in the substrate after providing the active and passive areas, and oxidizing the plurality of slots. The method further comprises providing metal in each of the plurality of slots, providing a dielectric coating over the slots, and providing etched contacts in select areas remote from the location of the slots. Additionally, the method provides an additional layer of metal that interconnects the contacts and the buried metal in select areas where contacts were etched, resulting in metal of three levels; and provides one level of the metal is on a top surface and two levels of the metal that comprise a buried power buss (BPB).

Claim Rejections – 35 USC 103

The Examiner states,

**Claims 1-6, 8 and 10-19 (all as best understood) are rejected under 35 U.S.C. 103(a) as being unpatentable over Rhodes (US 2005/0074966 A1) in view of Choi et al. (5,629,238; hereinafter “Choi”).**

**Claim 9 (as best understood) is rejected under 35 U.S.C. 103(as) as being unpatentable over Rhodes (in view of Choi) as applied to claim 1 above,**

**and further in view of Sahara et al. (4,764,804; hereinafter "Sahara") and Lin et al. (5,450,283; hereinafter "Lin").**

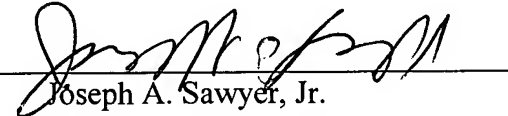
Applicant respectfully traverses these rejections since none of the references either singly or in combination teach one layer on a top surface comprising one level that is on a top surface and two levels that are buried to provide a buried power buss as recited in claim 1. This recitation in combination with the other elements of the claim is therefore allowable thereover.

Claims 2, 6, 7, 9, 13 and 16, and 18 are allowable since they depend from an allowable base claim. Accordingly, Applicant respectfully requests reconsideration and allowance of the claims as now presented.

In view of the foregoing, Applicant's attorney believes that this application is in condition for allowance. Should any unresolved issues remain, Examiner is invited to call Applicant's attorney at the telephone number indicated below.

Respectfully submitted,

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Joseph A. Sawyer, Jr.  
Sawyer Law Group LLP  
Attorney for Applicant  
Reg. No. 30,801  
(650) 493-4540